

from Electronics and Aerospace **Components**

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Microcare: Cleaning, Coating and Carrier Fluids



Contamination Removal

- TM 3 types of contaminant
 - ³/₄ Particulates (LOx, LASER, Optics)
 - ³/₄ organics
 - 3/4 Inorganics (No Clean / lead Free)
- TM What level of cleanliness do you need?
 - 3/4 Visual Specification
 - ³⁄₄ 2+ micron or particle count spec?
 - ³⁄₄ Cleanliness to 1 micron or submicron spec?
- TM Bear in mind your production environment when determining your cleanliness spec.

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Particulates – Not Easy to Clean

- TM Clean Rooms Are Rated From "Class 10,000" To "Class 1"
- TM Class 1 Clean Rooms Are*—
 - ~1,000 Times Cleaner Than A Hospital Operating Room
 - Allow Only One Particulate Per Cubic Foot Air
- TM 130 Trillion 0.5µ Particles Fit Inside A Ping Pong Ball
- TM Humans Shed About:
 - 100,000 Particles When You Blink
 - 5 Million Particles When You Walk
 - 10s Millions Of Particulate When You Move Vigorously



* Source: Rockwell's Dryden Engineering Co.

The Particulate Problem

One of the most challenging cleaning environments is inside a modern disk drive, where the read-write head "flies" over the surface of the platter. Here's how typical particulate compares:

Typical Human Hair 75µ-90µ







Methods of Particulate Removal

Large Particulate (>1,000µ)



Mechanical Action (Gravitational & Inertial Forces)

Medium Particulate



Chemical Action (Gravitational & Intermolecular Forces)







Chemical choices

- TM Aqueous
- TM Hydrocarbons
- TM Oxygenated
- TM Halocarbons (Fluorinated)
 - 3/4 Low Surface Tension
 - 3/4 Low Viscosity
 - 3/4 High Molecular density
 - 3/4 Non-flammable
 - 3/4 Good toxicity



Removing Lead-Free and No-Clean Fluxes from Modern PCBs

- TM The importance of cleaning:
 - 3/4 Remove harmful residues
 - ³/₄ Application of conformal coating
 - 3/4 Visual appearance



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Introduction

TM Manual cleaning methods



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Introduction

TM Bulk cleaning methods



Solvent Cleaning / Vapor Degreaser



Cleanliness Specification for Flux Removal

- TM Should be written with equipment and chemistry in mind.
 - ³⁄₄ Aqueous Cleaning for mass production of circuit boards.
 - ‰ Many chemistries / equipment suppliers available.
 - $\%\,$ Aqueous chemistry has a lower success threshold at

1 micron stand-offs

³⁄₄ Solvent Cleaning can achieve cleanliness down to the Angstrom level



Study on new solvent cleaners

- TM Evaluate 3 different no-clean flux formulations
- TM Evaluate 7 different no-clean, lead-free or hightemperature solder paste formulations
- TM Compare cleaning capability of new vapor degreasing formulations with classic vapor degreasing solvents
- TM Confirm cleaning will improve and not compromise product performance



Evaluated Fluxes and Solder Pastes						
Paste/Flux	Туре	No-Clean	Lead-Free			
AIM 217	Flux	\checkmark	NA			
AIM NC Paste Flux	Flux	\checkmark	NA			
AIM Flux Pen	Flux	\checkmark	NA			
AIM M8	Solder Paste	\checkmark	\checkmark			
AIM RMA258-15R	Rosin-based Solder Paste	Х	Х			
Loctite GC3W	Water-Soluble Solder Paste	\checkmark	\checkmark			
Alpha OM350	Solder Paste	\checkmark	\checkmark			
Indium 8.9HF1	Solder Paste	\checkmark	\checkmark			
Loctite GC10	Solder Paste	\checkmark	\checkmark			
Indium SMQ92-J	Solder Paste	\checkmark	Х			
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- TM Confirm similar cleaning process to typical vapor degreasing solvents
- TM Confirm improved removal of "white residues"
- TM Confirm improved removal of no-clean and hightemperature fluxes



- TM Clean standard test boards containing flux and solder pastes with Solvent A, Solvent B and a "Classic Solvent"
- TM Conduct visual analysis of the cleaning results at 35x magnification
- TM Photograph results for a visual comparison of cleaning capability



- TM B-36 coupons reflowed with each paste
- TM 6 coupons for each paste
- TM 2 coupons cleaned in each solvent



- TM Cleaning Cycle:
 - 3/4 30 seconds vapor
 - 3/4 5 minute boiling immersion
 - 3/4 5 minute rinse immersion
 - 3/4 30 seconds vapor
- TM Total cleaning time of 11 minutes



Visual Results- Alpha OM340

Before Cleaning

Classic Solvent

Solvent A

Solvent B

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Visual Results- Indium 8.9



Visual Results-Loctite GC10



Visual Results-Loctite GC3



SIR Evaluation

- TM Confirm the cleaning capability of the two solvent formulations via SIR testing
- TM Confirm removal of dendrite-forming ingredients
- TM Confirm that no detrimental ingredients are left behind by cleaner
- TM Confirm that partial cleaning of flux residue does not result in circuit failure



SIR Evaluation

- TM Repeat cleaning procedure used for the visual cleaning study
- TM Clean test boards in Solvent A and Solvent B
- TM Submit cleaned boards to an outside testing facility for SIR analysis



SIR Evaluation Procedure

- 1. All boards visually examined before cleaning
 - 10-40x magnification
- 2. All boards cleaned according to cleaning cycle
 - Total cleaning time of 21 minutes
- 3. Boards immediately analyzed visually
 - 10-40x magnification
- 4. Packaged and shipped to SIR lab



SIR Evaluation Procedure

TM SIR method followed IPC-TM-650 Method 2.6.3.3, requirements per IPC J-STD-004A, paragraph 3.2.4.5

EQUIPMENT LIST

ID	Manufacturer	Equipment Name	Serial / Model Number	Calibration Date	Calibration Due Date
CH-29	Thermotron	Environmental Test Chamber	45250/SM-16- 8200	20-Apr-2016	30-Apr-2017
E-54	Concoat	Auto-Sir	12861/256 Channel Rack- mount	9-Feb-2016	9-Feb-2017
E-76	Concoat	Auto-Sir	18811/256 Rack	8-Feb-2016	8-Feb-2017
MS-23	Olympus	Microscope and Camera	SZX16	30-Nov-2015	31-May-2017
S-26	JBC	Soldering Station - Auto Feed	159368/AL-1A	18-Apr-2016	30-Apr-2017



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SIR Testing Results

- TM All 10 fluxes passed SIR testing after cleaning in both Solvent A and Solvent B
- TM 4 out of 10 fluxes failed SIR testing if no cleaning was performed



Conclusions of Visual Study

- TM Simple cleaning cycle- 11 minutes total time
- TM Immersion in boiling liquid is necessary
- TM Improved removal of white residues
- TM Consistently cleaner results than "Classic Solvent"
- TM Ability to remove no-clean, high-temperature, leadfree and water-soluble residues



Conclusions of SIR Study

- TM Resistance readings were consistent across all trace pads on all boards
- TM Incomplete cleaning did not result in formation of detrimental compounds
- TM Cleaning formula did not leave behind any detrimental compounds
- TM Cleaning prevented failures for pastes that may have otherwise failed



Presentation Summary

- TM Halocarbons and their mixtures can be used for Critical cleaning to remove
 - 3/4 Particulates
 - ‰ LOx/ GOx
 - % LASERS / Optics
 - % Disc Drives
 - 3/4 Stubborn salts and White Residues
 - ³⁄₄ Residues that can aid in the formation of Dendrites
 - **%** Electronics and Electronic assemblies
- TM Contact MicroCare regarding more information on these types of fluids.



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